



Product Change Notification - KSRA-04XXPR967

Date:

08 May 2020

Product Category:

8-bit Microcontrollers

Affected CPNs:**Notification subject:**

CCB 3702.002 Final Notice: Qualification of NSEB as a new assembly site for selected Atmel ATTINY87, ATTINY167 and AT90PWM81 device families available in 32L VQFN (5x5x0.9mm) package using palladium coated copper with gold flash (CuPdAu) bond wire.

Notification text:**PCN Status:**

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of NSEB as a new assembly site for selected Atmel ATTINY87, ATTINY167 and AT90PWM81 device families available in 32L VQFN (5x5x0.9mm) package using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre Change:

Assembled at ATP7 using palladium coated copper (PdCu) or palladium coated gold (AuPd) bond wire, AMK-06 die attach, and C194 lead frame material

Post Change:

Assembled at NSEB using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and EFTEC 64T lead frame material

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Amkor Technology Philippines (P3/P4), INC. / ATP7)	UTAC Thai Limited LTD. / NSEB
Wire material	PdCu / AuPd	CuPdAu
Die attach material	AMK-06	8600
Molding compound material	G700	G700
Lead frame material	C194	EFTEC 64T

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying NSEB as a new assembly site

Change Implementation Status:

In Progress

Estimated First Ship Date:

July 17, 2020 (date code: 2029)



NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

Workweek	May 2020					📅📧📧📧	July 2020				
	18	19	20	21	22		27	28	29	30	31
Qual Report Availability		X									
Final PCN Issue Date		X									
Estimated Implementation Date									X		

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

May 08, 2020: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on July 17, 2020.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_KSRA-04XXPR967_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

ATTINY87-MU

ATTINY87-MUR

ATTINY167-MUR

AT90PWM81EP-16MN

ATTINY167-MU

ATTINY87-A15MD

AT90PWM81-16MN

AT90PWM81-16MF